

* 所有原料材质, 生产制程, 电镀必须符合HTR要求

备注:

1. 材质:

- 1.1 胶芯: LCP UL94V-0
- 1.2 铁壳: SUS304-3/4H HV300-330 T=0.15mm W=27mm.
- 1.3 端子: C5210-EH HV210-230 T=0.15mm W=17.5mm.

2. 电镀规格:

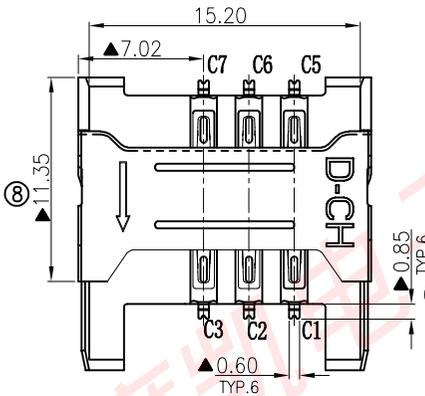
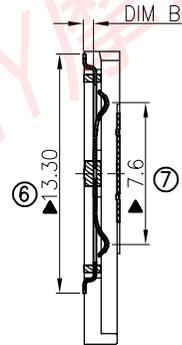
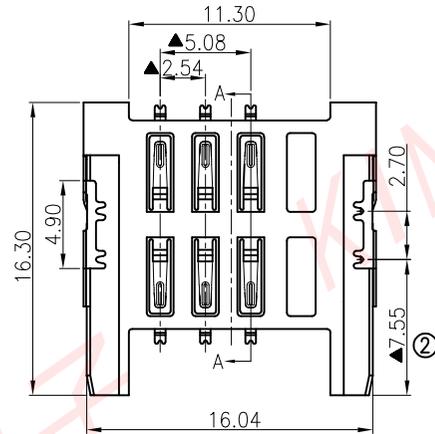
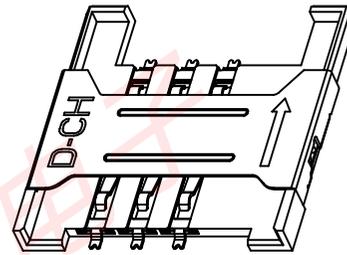
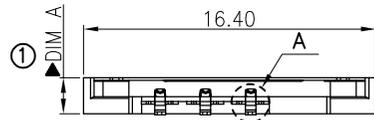
- 2.1 端子: 接触区域刷金1u' 以上, 焊脚区刷金1u' 以上, 镍底50u' 以上.
- 2.2 铁壳: 接触区域刷金1u' 以上, 镍底50u' 以上.

3. 主要特性:

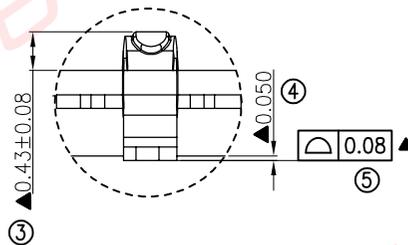
- 3.1 额定电流: 0.5A
- 3.2 额定电压: 30V
- 3.3 接触阻抗: 30mΩ MAX
- 3.4 绝缘阻抗: 100MΩ MIN 100V DC
- 3.5 耐压测试: 100V AC
- 3.6 沾锡性: 温度260° C±5° C (无铅) /245° C±5° C (有铅), 时间5±0.5s
- 3.7 使用寿命: 5000次
- 3.8 耐温性: 烤箱测试: 温度250±5° C, 时间2分钟
- 3.9 工作环境: 温度: -20° C~+85° C; 湿度: 80% MAX

4. ▲为重点尺寸.

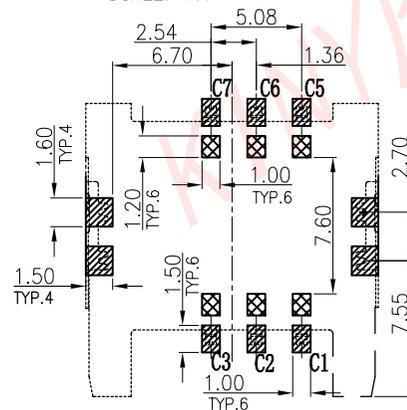
5. 标记⊗为制程管制尺寸, 必须测量.



SECTION: A-A
SCALE: 1:1



DETAIL "A"
SCALE 5:1



RECOMMEND P.C.B. LAYOUT
TOLERANCE ±0.05

SIM Card Pin Assignments

SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
C6	Vpp
C7	DATA

☒ THESE AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
 ☒ SMT SOLDER AREA

PART No.	DIM A	DIM B
SM180-T1251-01-W	1.80	0.38
SM200-T1251-01-W	2.00	0.58

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
 UNLESS OTHERWISE SPECIFIABLE
 DIMENSION TOLERANCE
 X.X: ± 0.38
 X.XX: ± 0.25
 X.XXX: ± 0.15
 ANGULAR: ± 3'

PRODUCT NAME :	DRAWING:	DATE:
SIM CARD H1.8 6PIN	FAJI	2020.11.02
PRODUCT NO. :	CHECK:	DATE:
SM180-T1251-01-W	Alex	2020.11.02
DRAWING NO. :	APPROVED:	DATE:
D-SM180-T1251-01-W	Alex	2020.11.02
SCALE: 1:1	DWG ID: C D	REV.: A
		PAGE: 1 of 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1		NEW RELEASE	FAJI	2020.11.02